L Number	Hits	Search Text	DB Tim	e stamp
1	227	257/687		4/07/08 20:49
		·	EPO; JPO; DERWENT; IBM TDB	
2	1177	257/687	USPAT; 200 US-PGPUB; EPO; JPO;	4/07/08 20:58
3	1684	257/704	US-PGPUB;	4/07/08 21:08
4	1397	257/762	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	4/07/08 21:35
5	1854	257/763	IBM_TDB USPAT; 200 US-PGPUB; EPO; JPO;	4/07/08 21:52
6	812	257/766	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	4/07/08 21:53
_	317	257/738	IBM_TDB US-PGPUB; 200 EPO; JPO; DERWENT;	4/07/08 20:49
_	2488	257/738 and (ball or bump or BGA or array)	US-PGPUB; EPO; JPO; DERWENT;	4/07/08 12:24
_	2208	257/738 and (ball or bump or BGA or array or flip)	IBM_TDB USPAT 200	4/07/08 12:24
-	2510	257/738 and (ball or bump or BGA or array or flip)	US-PGPUB; EPO; JPO;	4/07/08 12:25
_	2488	257/738 and (ball or bump or BGA or array)	US-PGPUB; EPO; JPO; DERWENT;	4/07/08 12:25
	2188 1954	257/738 and (ball or bump or BGA or array) 257/738 and (ball or bump or BGA or array) and wir\$3	= =	04/07/08 12:25 04/07/08 13:46
-	1954	257/738 and (ball or bump or BGA or array) and wir\$3	IBM_TDB	04/07/08 13:58
_	2670	257/738	IBM_TDB USPAT; 200 US-PGPUB; EPO; JPO;	04/07/08 13:51
-	716	257/738 not (257/738 and (ball or bump or BGA or array) and wir\$3)	DERWENT; IBM_TDB	04/07/08 13:51

-	5257	257/666	USPAT; US-PGPUB;	2004/07/08 13:58
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1673	257/666 and (ball or bump or BGA or array)	USPAT;	2004/07/08 14:27
		and wir\$3	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	323	257/667 and (ball or bump or BGA or array)	USPĀT;	2004/07/08 14:27
		and wir\$3	US-PGPUB;	
			EPO; JPO; DERWENT;	
•			IBM TDB	
_	3167	257/666	USPAT	2004/07/08 15:34
-	1671	257/666 not (257/666 and (ball or bump or	USPAT	2004/07/08 14:29
l		BGA or array) and wir\$3)		0004/07/00 14 31
j -	0	conductive near epoxy with 257/777	USPAT USPAT	2004/07/08 14:31 2004/07/08 14:35
-	34	electrically near conductive near epoxy and 257/777	OSEMI	2004/07/00 14:33
-	39	electrically near conductive near epoxy	USPAT	2004/07/08 14:34
		and (438/108 or 438/109)		
-	188	conductive near epoxy and 257/777	USPAT	2004/07/08 14:35
-	61	electrically with conductive near epoxy and 257/777	USPAT	2004/07/08 14:38
_	98	electrically with conductive near epoxy	USPAT	2004/07/08 14:40
		and (257/777 or 438/108 or 438/109)		
-	134	electrically with conductive near epoxy	USPAT	2004/07/08 14:50
		and (257/777 or 438/108 or 438/109 or		
1_	141	257/686) electrically with (conductive or "Ag" or	USPAT	2004/07/08 14:56
	+	silver) near epoxy and (257/777 or 438/108	"	
		or 438/109 or 257/686)		
-	0	electrically with (conductive or "Ag" or	JPO	2004/07/08 14:54
		silver) near epoxy and (257/777 or 438/108 or 438/109 or 257/686)		
_	172	electrically with (conductive or "Ag" or	USPAT	2004/07/08 15:21
		silver) near epoxy and (257/777 or 438/108		
		or 438/109 or 257/686 or 361/760)		
_	320	electrically with (conductive or "Ag" or	USPAT	2004/07/08 15:22
		silver) with epoxy and (257/777 or 438/108 or 438/109 or 257/686 or 361/760)		
-	235	electrically with (conductive or "Ag" or	USPAT	2004/07/08 15:22
		silver) with epoxy and (257/777 or 438/108		
		or 438/109 or 257/686 or 361/760) and		
_	685	(ball or bump) 257/667	USPAT	2004/07/08 15:34
-	945	257/667	USPAT;	2004/07/08 16:05
			US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	778	257/673	USPAT;	2004/07/08 16:15
			US-PGPUB;	
			EPO; JPO;	
1			DERWENT; IBM TDB	
_	3181	257/676	USPAT;	2004/07/08 16:10
	1		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	2245	257/676	IBM_TDB USPAT	2004/07/08 16:11
_	3329	257/773	USPAT;	2004/07/08 16:15
			US-PGPUB;	
	İ		EPO; JPO;	
			DERWENT; IBM TDB	
_	2717	257/773	USPAT	2004/07/08 16:39
-	2719	257/774	USPAT	2004/07/08 16:55
-	972	257/776	USPAT	2004/07/08 16:55

	1 44.50		TIODAM.	0004/07/00 17 10
-	1162	257/776	USPAT;	2004/07/08 17:10
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2518	257/784	USPAT;	2004/07/08 17:10
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	Ì		IBM TDB	
_	1783	257/784	USPAT	2004/07/08 17:19
_	861	257/684	USPAT	2004/07/08 17:20
_	1062	257/684	USPAT;	2004/07/08 17:45
			US-PGPUB;	
			EPO; JPO;	1
			DERWENT;	
İ			IBM TDB]
\ _	2342	257/698	USPAT;	2004/07/08 17:49
1	2542	2317 030	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	3932	257/778	USPAT;	2004/07/08 17:49
-	3932	2317110	US-PGPUB;	2001, 07, 00 17115
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	2410	257/770	USPAT	2004/07/08 18:11
-	3410	· · · · · · · · · · · · · · · · · · ·	USPAT	2004/07/08 18:57
-	2231	,	USPAT	2004/07/08 18:57
-	902		USPAT;	2004/07/08 18:58
-	1001	257/781	US-PGPUB;	2004/07/00 18.38
			EPO; JPO;	1
1				
			DERWENT;	
ì	1		IBM TDB	